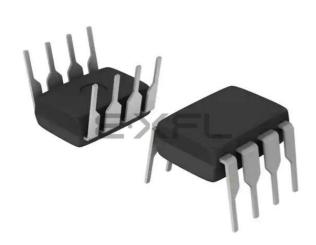
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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	3
Program Memory Size	896B (512 x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 3x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic10f322-e-p

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

5.1 Power-On Reset (POR)

The POR circuit holds the device in Reset until VDD has reached an acceptable level for minimum operation. Slow rising VDD, fast operating speeds or analog performance may require greater than minimum VDD. The PWRT, BOR or MCLR features can be used to extend the start-up period until all device operation conditions have been met.

5.1.1 POWER-UP TIMER (PWRT)

The Power-up Timer provides a nominal 64 ms timeout on POR or Brown-out Reset.

The device is held in Reset as long as PWRT is active. The PWRT delay allows additional time for the VDD to rise to an acceptable level. The Power-up Timer is enabled by clearing the PWRTE bit in Configuration Word.

The Power-up Timer starts after the release of the POR and BOR.

For additional information, refer to Application Note AN607, *"Power-up Trouble Shooting"* (DS00607).

5.2 Brown-Out Reset (BOR)

The BOR circuit holds the device in Reset when VDD reaches a selectable minimum level. Between the POR and BOR, complete voltage range coverage for execution protection can be implemented.

The Brown-out Reset module has four operating modes controlled by the BOREN<1:0> bits in Configuration Word. The four operating modes are:

- BOR is always on
- BOR is off when in Sleep
- · BOR is controlled by software
- · BOR is always off

Refer to Table 5-1 for more information.

The Brown-out Reset voltage level is selectable by configuring the BORV bit in Register 3-1.

A VDD noise rejection filter prevents the BOR from triggering on small events. If VDD falls below VBOR for a duration greater than parameter TBORDC, the device will reset. See Figure 5-2 for more information.

BOREN<1:0>	SBOREN	Device Mode	BOR Mode	Device Operation upon: Release of POR/Wake- up from Sleep
11	Х	Х	Active	Waits for BOR ready ⁽¹⁾ (BORRDY = 1)
1.0		Awake	Active	Weite for POP ready (POPPDY = 1)
10	Х	Sleep	Disabled	Waits for BOR ready (BORRDY = 1)
0.1	1	Х	Active	Waits for BOR ready ⁽¹⁾ (BORRDY = 1)
01	0	х	Disabled	Baging immediately (BOBBDY =)
00	Х	х	Disabled	Begins immediately (BORRDY = x)

TABLE 5-1: BOR OPERATING MODES

Note 1: In these specific cases, "Release of POR" and "Wake-up from Sleep", there is no delay in start-up. The BOR ready flag, (BORRDY = 1), will be set before the CPU is ready to execute instructions because the BOR circuit is forced on by the BOREN<1:0> bits.

5.2.1 BOR IS ALWAYS ON

When the BOREN bits of Configuration Word are programmed to '11', the BOR is always on. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is active during Sleep. The BOR does not delay wake-up from Sleep.

5.2.2 BOR IS OFF IN SLEEP

When the BOREN bits of Configuration Word are programmed to '10', the BOR is on, except in Sleep. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is not active during Sleep. The device wake-up will be delayed until the BOR is ready.

5.2.3 BOR CONTROLLED BY SOFTWARE

When the BOREN bits of Configuration Word are programmed to '01', the BOR is controlled by the SBOREN bit of the BORCON register. The device startup is not delayed by the BOR ready condition or the VDD level.

BOR protection begins as soon as the BOR circuit is ready. The status of the BOR circuit is reflected in the BORRDY bit of the BORCON register.

BOR protection is unchanged by Sleep.

6.3 Interrupts During Sleep

Some interrupts can be used to wake from Sleep. To wake from Sleep, the peripheral must be able to operate without the system clock. The interrupt source must have the appropriate Interrupt Enable bit(s) set prior to entering Sleep.

On waking from Sleep, if the GIE bit is also set, the processor will branch to the interrupt vector. Otherwise, the processor will continue executing instructions after the SLEEP instruction. The instruction directly after the SLEEP instruction will always be executed before branching to the ISR. Refer to the Section 7.0 "Power-Down Mode (Sleep)" for more details.

6.4 INT Pin

The INT pin can be used to generate an asynchronous edge-triggered interrupt. This interrupt is enabled by setting the INTE bit of the INTCON register. The INTEDG bit of the OPTION_REG register determines on which edge the interrupt will occur. When the INTEDG bit is set, the rising edge will cause the interrupt. When the INTEDG bit is clear, the falling edge will cause the interrupt. The INTF bit of the INTCON register will be set when a valid edge appears on the INT pin. If the GIE and INTE bits are also set, the processor will redirect program execution to the interrupt vector.

6.5 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt (e.g., W and STATUS registers). This must be implemented in software.

Temporary holding registers W_TEMP and STATUS_TEMP should be placed in the last 16 bytes of GPR (see Table 1-2). This makes context save and restore operations simpler. The code shown in Example 6-1 can be used to:

- Store the W register
- · Store the STATUS register
- · Execute the ISR code
- Restore the Status (and Bank Select Bit register)
- · Restore the W register
- Note: These devices do not require saving the PCLATH. However, if computed GOTOS are used in both the ISR and the main code, the PCLATH must be saved and restored in the ISR.

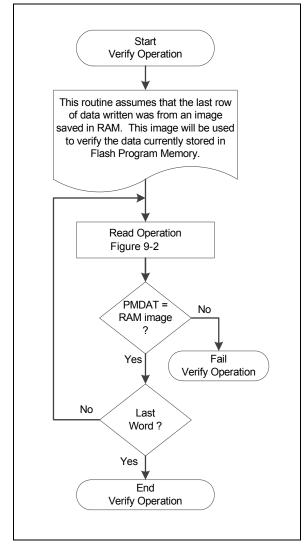
EXAMPLE 6-1: SAVING STATUS AND W REGISTERS IN RAM

MOVWF SWAPF	W_TEMP STATUS,W	;Copy W to TEMP register ;Swap status to be saved into W
MOLTHE		;Swaps are used because they do not affect the status bits
MOVWF :	STATUS_TEMP	;Save status to bank zero STATUS_TEMP register
:(ISR)		;Insert user code here
SWAPF	STATUS_TEMP,W	;Swap STATUS_TEMP register into W
		;(sets bank to original state)
MOVWF	STATUS	;Move W into STATUS register
SWAPF	W_TEMP,F	;Swap W_TEMP
SWAPF	W_TEMP,W	;Swap W_TEMP into W

9.5 Write Verify

It is considered good programming practice to verify that program memory writes agree with the intended value. Since program memory is stored as a full page then the stored program memory contents are compared with the intended data stored in RAM after the last write is complete.

FIGURE 9-8: FLASH PROGRAM MEMORY VERIFY FLOWCHART



U-1 ⁽¹) R/W-0/0	R/W-0/0	R/W/HC-0/0	R/W/HC-0/q ⁽²⁾	R/W-0/0	R/S/HC-0/0	R/S/HC-0/0				
_	CFGS	LWLO	FREE	WRERR	WREN	WR	RD				
bit 7							bit C				
logondi											
L egend: R = Read	able bit	W = Writable	bit	U = Unimplemer	nted bit. read a	as '0'					
	in only be set	x = Bit is unk		-n/n = Value at P	-		er Resets				
'1' = Bit is	•	'0' = Bit is cle		HC = Bit is clear							
bit 7	Unimpleme	nted: Read as	'1'								
bit 6		iguration Selec									
				evice ID Registers	5						
hit E		Flash program	-								
bit 5		Write Latches		write latch is load	led/undated o	n the next WR (ommand				
				e latch is loaded/							
			•	ext WR command		•	0				
bit 4	FREE: Progr	FREE: Program Flash Erase Enable bit									
		1 = Performs an erase operation on the next WR command (hardware cleared upon completion)									
		0 = Performs an write operation on the next WR command									
bit 3		WRERR: Program/Erase Error Flag bit									
		1 = Condition indicates an improper program or erase sequence attempt or termination (bit is se automatically on any set attempt (write (1)) of the WP bit)									
		automatically on any set attempt (write '1') of the WR bit). 0 = The program or erase operation completed normally.									
bit 2											
	-	WREN: Program/Erase Enable bit 1 = Allows program/erase cycles									
		0 = Inhibits programming/erasing of program Flash									
bit 1	WR: Write C	WR: Write Control bit									
		1 = Initiates a program Flash program/erase operation.									
				is cleared by har	dware once o	peration is com	olete.				
				ed) in software. is complete and i	nactive						
bit 0	RD: Read Co	•			naouvo.						
			sh read. Read	takes one cycle.	RD is cleared	in hardware. T	he RD bit ca				
		set (not cleared									
	0 = Does no	ot initiate a prog	ram Flash read	d.							
Note 1:	Unimplemented b										
2:	The WRERR bit is (WR = 1).	automatically	set by hardwar	e when a program	n memory write	e or erase opera	ition is started				
э.		nored during a		on oraca anarati		١					

REGISTER 9-5: PMCON1: PROGRAM MEMORY CONTROL 1 REGISTER

3: The LWLO bit is ignored during a program memory erase operation (FREE = 1).

10.2 Register Definitions: PORTA

REGISTER 10-1: PORTA: PORTA REGISTER

U-0	U-0	U-0	U-0	R-x/x	R/W-x/x	R/W-x/x	R/W-x/x
—	—	—	—	RA3	RA2	RA1	RA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 Unimplemented: Read as '0'

bit 3-0 RA<3:0>: PORTA I/O Value bits (RA3 is read-only)

Note 1: Writes to PORTx are actually written to the corresponding LATx register. Reads from PORTx register return actual I/O pin values.

REGISTER 10-2: TRISA: PORTA TRI-STATE REGISTER

U-0	U-0	U-0	U-0	U-1	R/W-1/1	R/W-1/1	R/W-1/1
—	—	—	—	(1)	TRISA2	TRISA1	TRISA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4	Unimplemented: Read as '0'.
bit 3	Unimplemented: Read as '1'.
bit 2-0	TRISA<2:0>: RA<2:0> Port I/O Tri-State Control bits
	 Port output driver is disabled Port output driver is enabled

Note 1: Unimplemented, read as '1'.

15.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- · Channel selection
- ADC conversion clock source
- · Interrupt control

15.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 10.0 "I/O Port"** for more information.

Note:	Analog voltages on any pin that is defined
	as a digital input may cause the input buf-
	fer to conduct excess current.

15.1.2 CHANNEL SELECTION

There are up to five channel selections available:

- AN<2:0> pins
- Temperature Indicator
- FVR (Fixed Voltage Reference) Output

Refer to Section 12.0 "Fixed Voltage Reference (FVR)" and Section 14.0 "Temperature Indicator Module" for more information on these channel selections.

The CHS bits of the ADCON register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay is required before starting the next conversion. Refer to **Section 15.2 "ADC Operation"** for more information.

15.1.3 ADC VOLTAGE REFERENCE

There is no external voltage reference connections to the ADC. Only VDD can be used as a reference source. The FVR is only available as an input channel and not a VREF+ input to the ADC.

15.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON register (Register 15-1). There are seven possible clock options:

- · Fosc/2
- Fosc/4
- Fosc/8
- Fosc/16
- Fosc/32
- Fosc/64
- FRC (dedicated internal RC oscillator)

The time to complete one bit conversion is defined as TAD. One full 8-bit conversion requires 9.5 TAD periods as shown in Figure 15-2.

For correct conversion, the appropriate TAD specification must be met. Refer to the A/D conversion requirements in **Section 24.0 "Electrical Specifications"** for more information. Table 15-1 gives examples of appropriate ADC clock selections.

Note: Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

TABLE 15-2: SUMMARY OF REGISTERS ASSOCIATED WITH ADC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ADCON	ADCS<2:0>			CHS<2:0>			GO/DONE	ADON	88
ADRES	ADRES<7:0>					89			
ANSELA	—	_	_	—	—	ANSA2	ANSA1	ANSA0	70
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	_	_	ADFVF	۲<1:0>	78
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	40
PIE1	—	ADIE	_	NCO1IE	CLC1IE	-	TMR2IE	—	41
PIR1	—	ADIF	—	NCO1IF	CLC1IF	—	TMR2IF	_	42
TRISA	_	—	_	—	_	TRISA2	TRISA1	TRISA0	69

Legend: x = unknown, u = unchanged, — = unimplemented read as '0', q = value depends on condition. Shaded cells are not used for ADC module.

U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0			
_		TOUTF	°S<3:0>		TMR2ON	T2CKF	°S<1:0>			
bit 7							bit			
Legend:										
R = Readat	ole bit	W = Writable	bit	U = Unimpler	mented bit, read	as '0'				
u = Bit is ur	changed	x = Bit is unkr	nown		at POR and BO		other Resets			
'1' = Bit is s	-	'0' = Bit is cle								
			_							
bit 7	-	nted: Read as '								
bit 6-3		0>: Timer2 Out	put Postscale	r Select bits						
		1111 = 1:16 Postscaler								
		1110 = 1:15 Postscaler								
		1101 = 1:14 Postscaler 1100 = 1:13 Postscaler								
		100 = 1.13 Postscaler $1011 = 1.12 Postscaler$								
		1011 - 1.12 Postscaler $1010 = 1.11 Postscaler$								
		1001 = 1:10 Postscaler								
	1000 = 1 :9	1000 = 1:9 Postscaler								
	0111 = 1 :8	Postscaler								
		0110 = 1:7 Postscaler								
		0101 = 1:6 Postscaler								
	0100 = 1:5									
	0011 = 1:4									
	0010 = 1:3									
		0001 = 1:2 Postscaler 0000 = 1:1 Postscaler								
bit 2	TMR2ON: T									
	1 = Timer2 i									
	0 = Timer2 i	is off								
bit 1-0	T2CKPS<1:	0>: Timer2 Cloc	k Prescale Se	elect bits						
	11 = Presc	T2CKPS<1:0>: Timer2 Clock Prescale Select bits 11 = Prescaler is 64								
		10 = Prescaler is 16								
	01 = Presc	aler is 4								
	00 = Presc	aler is 1								
TABLE 17-	1: SUMMAR	RY OF REGIS	TERS ASSO	CIATED WIT	H TIMER2					

REGISTER 17-1: T2CON: TIMER2 CONTROL REGISTER

TABLE '	17-1: \$	SUMMAR	Y OF REG	ISTERS A	ASSOCIATED) WITH TI	MER2

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	40
PIE1	_	ADIE		NCO1IE	CLC1IE		TMR2IE		41
PIR1	-	ADIF	_	NCO1IF	CLC1IF	_	TMR2IF		42
PR2		Timer2 module Period Register					96		
TMR2	Timer2 module Register					96			
T2CON	_	TOUTPS<3:0> TMR2ON T2CKPS<1:0>			97				

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used for Timer2 module.

19.0 CONFIGURABLE LOGIC CELL (CLC)

The Configurable Logic Cell (CLCx) provides programmable logic that operates outside the speed limitations of software execution. The logic cell selects any combination of the eight input signals and through the use of configurable gates reduces the selected inputs to four logic lines that drive one of eight selectable single-output logic functions.

Input sources are a combination of the following:

- Two I/O pins
- Internal clocks
- · Peripherals
- Register bits

The output can be directed internally to peripherals and to an output pin.

Refer to Figure 19-1 for a simplified diagram showing signal flow through the CLCx.

Possible configurations include:

- Combinatorial Logic
 - AND
 - NAND
 - AND-OR
 - AND-OR-INVERT
 - OR-XOR
 - OR-XNOR
- Latches
 - S-R
 - Clocked D with Set and Reset
 - Transparent D with Set and Reset
 - Clocked J-K with Reset

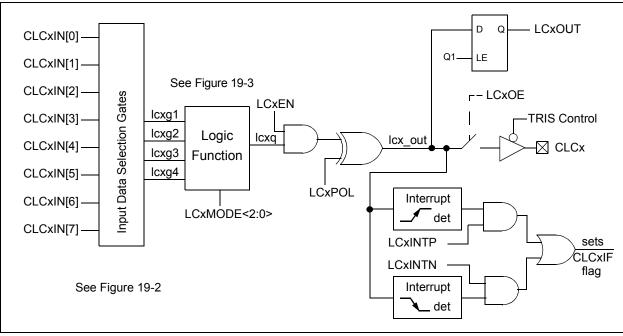
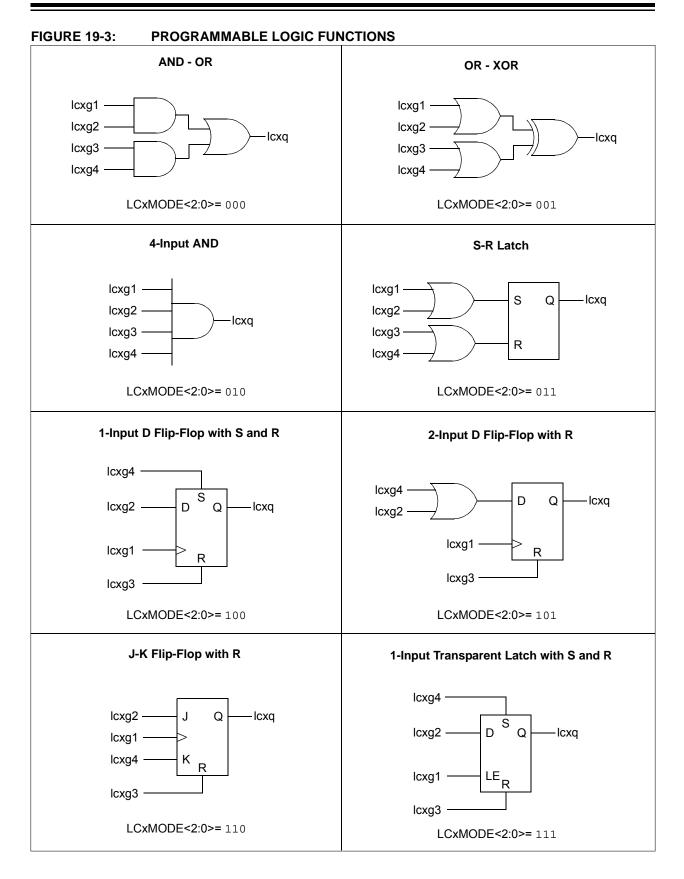
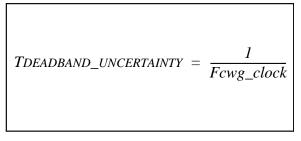


FIGURE 19-1: CLCx SIMPLIFIED BLOCK DIAGRAM



EQUATION 21-1: DEAD-BAND DELAY TIME UNCERTAINTY



EXAMPLE 21-1: DEAD-BAND DELAY TIME UNCERTAINTY

$$Fcwg_clock = 16 MHz$$

Therefore:
$$TDEADBAND_UNCERTAINTY = \frac{1}{Fcwg_clock}$$
$$= \frac{1}{16 MHz}$$
$$= 625 ns$$

21.12 CWG Control Registers

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	R/W-0/0
GxEN	GxOEB	GxOEA	GxPOLB	GxPOLA	_	_	GxCS0
bit 7							bit 0
Legend:							
R = Readab	le bit	W = Writable	bit	U = Unimplen	nented bit, read	as '0'	
u = Bit is un	changed	x = Bit is unk	x = Bit is unknown		at POR and BO	R/Value at all	other Resets
'1' = Bit is se	et	'0' = Bit is cle	ared	q = Value dep	ends on condit	ion	
bit 7	GxEN: CWG	x Enable bit					
	1 = Module i						
	0 = Module i						
bit 6				a .			
		is available on is not available					
bit 5				le l/O pin			
DIL 5		GxOEA: CWGxA Output Enable bit 1 = CWGxA is available on appropriate					
		is not available		•			
bit 4		NGxB Output F					
		s inverted polar	•				
	0 = Output is	s normal polarit	y				
bit 3 GxPOLA: CWGxA Output Polarity bit		olarity bit					
		s inverted polar					
		s normal polarit	•				
bit 2-1	Unimplemer	nted: Read as '	0'				
bit 0		Gx Clock Source	e Select bit				
	1 = HFINTO	SC					

REGISTER 21-1: CWGxCON0: CWG CONTROL REGISTER 0

ADDLW	Add literal and W		
Syntax:	[label] ADDLW k		
Operands:	$0 \leq k \leq 255$		
Operation:	$(W) + k \to (W)$		
Status Affected:	C, DC, Z		
Description:	The contents of the W register are added to the 8-bit literal 'k' and the result is placed in the W register.		

BCF	Bit Clear f				
Syntax:	[label] BCF f,b				
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ 0 \leq b \leq 7 \end{array}$				
Operation:	$0 \rightarrow (f \le b >)$				
Status Affected:	None				
Description:	Bit 'b' in register 'f' is cleared.				

ADDWF	Add W and f				
Syntax:	[<i>label</i>] ADDWF f,d				
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$				
Operation:	(W) + (f) \rightarrow (destination)				
Status Affected:	C, DC, Z				
Description:	Add the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.				

BSF	Bit Set f
Syntax:	[<i>label</i>] BSF f,b
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ 0 \leq b \leq 7 \end{array}$
Operation:	$1 \rightarrow (f \le b >)$
Status Affected:	None
Description:	Bit 'b' in register 'f' is set.

ANDLW	AND literal with W
Syntax:	[<i>label</i>] ANDLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .AND. (k) \rightarrow (W)
Status Affected:	Z
Description:	The contents of W register are AND'ed with the 8-bit literal 'k'. The result is placed in the W register.

BTFSC	Bit Test f, Skip if Clear				
Syntax:	[label] BTFSC f,b				
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ 0 \leq b \leq 7 \end{array}$				
Operation:	skip if (f) = 0				
Status Affected:	None				
Description:	If bit 'b' in register 'f' is '1', the next instruction is executed. If bit 'b' in register 'f' is '0', the next instruction is discarded, and a NOP is executed instead, making this a 2-cycle instruction.				

ANDWF	AND W with f
Syntax:	[label] ANDWF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	(W) .AND. (f) \rightarrow (destination)
Status Affected:	Z
Description:	AND the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

DECFSZ	Decrement f, Skip if 0			
Syntax:	[<i>label</i>] DECFSZ f,d			
Operands:	$\begin{array}{l} 0\leq f\leq 127\\ d\in [0,1] \end{array}$			
Operation:	(f) - 1 \rightarrow (destination); skip if result = 0			
Status Affected:	None			
Description:	The contents of register 'f' are decremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'. If the result is '1', the next instruction is executed. If the result is '0', then a NOP is executed instead, making it a 2-cycle instruction.			

INCFSZ	Increment f, Skip if 0
Syntax:	[label] INCFSZ f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	(f) + 1 \rightarrow (destination), skip if result = 0
Status Affected:	None
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'. If the result is '1', the next instruction is executed. If the result is '0', a NOP is executed instead, making it a 2-cycle instruction.

GOTO	Unconditional Branch							
Syntax:	[<i>label</i>] GOTO k							
Operands:	$0 \le k \le 2047$							
Operation:	$k \rightarrow PC < 10:0>$ PCLATH<4:3> \rightarrow PC<12:11>							
Status Affected:	None							
Description:	GOTO is an unconditional branch. The 11-bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a 2-cycle instruction.							

IORLW	Inclusive OR literal with W						
Syntax:	[<i>label</i>] IORLW k						
Operands:	$0 \leq k \leq 255$						
Operation:	(W) .OR. $k \rightarrow$ (W)						
Status Affected:	Z						
Description:	The contents of the W register are OR'ed with the 8-bit literal 'k'. The result is placed in the W register.						

INCF	Increment f
Syntax:	[label] INCF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) + 1 \rightarrow (destination)
Status Affected:	Z
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

IORWF	Inclusive OR W with f							Inclusive OR W with f				
Syntax:	[<i>label</i>] IORWF f,d											
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$											
Operation:	(W) .OR. (f) \rightarrow (destination)											
Status Affected:	Z											
Description:	Inclusive OR the W register with register 'f'. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.											

MOVF	Move f
Syntax:	[<i>label</i>] MOVF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	$(f) \rightarrow (dest)$
Status Affected:	Z
Description:	The contents of register 'f' is moved to a destination dependent upon the status of 'd'. If $d = 0$, destination is W register. If $d = 1$, the destination is file register 'f' itself. $d = 1$ is useful to test a file register since Status flag Z is affected.
Words:	1
Cycles:	1
Example:	MOVF FSR, 0
	After Instruction W = value in FSR register Z = 1

MOVWF	Move W to f
Syntax:	[<i>label</i>] MOVWF f
Operands:	$0 \leq f \leq 127$
Operation:	$(W) \rightarrow (f)$
Status Affected:	None
Description:	Move data from W register to register 'f'.
Words:	1
Cycles:	1
Example:	MOVW OPTION_REG F
	Before Instruction $OPTION_REG = 0xFF$ W = 0x4F After Instruction $OPTION_REG = 0x4F$ W = 0x4F

MOVLW	Move literal to W					
Syntax:	[<i>label</i>] MOVLW k					
Operands:	$0 \leq k \leq 255$					
Operation:	$k \rightarrow (W)$					
Status Affected:	None					
Description:	The 8-bit literal 'k' is loaded into W register. The "don't cares" will assemble as '0's.					
Words:	1					
Cycles:	1					
Example:	MOVLW 0x5A					
	After Instruction W = 0x5A					

NOP	No Operation				
Syntax:	[label] NOP				
Operands:	None				
Operation:	No operation				
Status Affected:	None				
Description:	No operation.				
Words:	1				
Cycles:	1				
Example:	NOP				

FIGURE 24-5: CLOCK TIMING

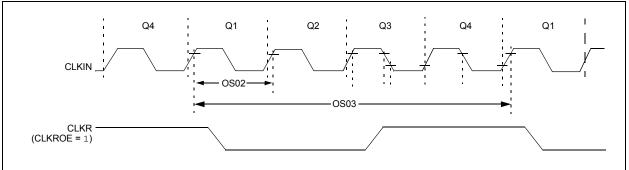


TABLE 24-6: CLOCK OSCILLATOR TIMING REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)								
Param No.	Sym Characteristic Min Typt Max Units Conditions							
OS01	Fosc	External CLKIN Frequency ⁽¹⁾	DC		20	MHz	EC mode	
OS02	Tosc	External CLKIN Period ⁽¹⁾	31.25	-	∞	ns	EC Oscillator mode	
OS03	TCY	Instruction Cycle Time ⁽¹⁾	200	Тсү	DC	ns	Tcy = 4/Fosc	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to CLKIN pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

TABLE 24-7: OSCILLATOR PARAMETERS

Standar	Standard Operating Conditions (unless otherwise stated)							
Param No. Sym. Characteristic		Freq. Tolerance	Min.	Тур†	Max.	Units	Conditions	
OS08	HFosc	Internal Calibrated HFINTOSC Frequency ⁽¹⁾	±3% -8 to +4%	_	16.0 16.0	—	MHz MHz	$\begin{array}{l} 0^{\circ}C \leq TA \leq +85^{\circ}C, \ VDD \geq 2.3V \\ -40^{\circ}C \leq TA \leq 125^{\circ}C \end{array}$
OS09	LFosc	Internal LFINTOSC Frequency	±25%	_	31	-	kHz	
OS10*	TWARM	HFINTOSC Wake-up from Sleep Start-up Time	—	_	5	8	μS	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

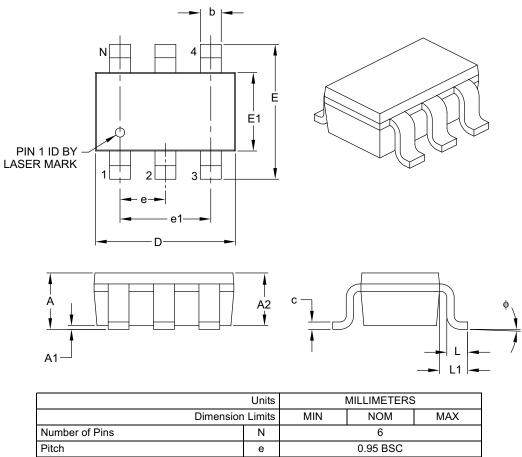
Note 1: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 μ F and 0.01 μ F values in parallel are recommended.

27.2 Package Details

The following sections give the technical details of the packages.

6-Lead Plastic Small Outline Transistor (OT) [SOT-23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Offita					
	Dimension Limits	MIN	NOM	MAX		
Number of Pins	N		6			
Pitch	е		0.95 BSC			
Outside Lead Pitch	e1		1.90 BSC			
Overall Height	А	0.90	-	1.45		
Molded Package Thickness	A2	0.89	-	1.30		
Standoff	A1	0.00	-	0.15		
Overall Width	E	2.20	2.20 – 3.20			
Molded Package Width	E1	1.30 – 1.80				
Overall Length	D	2.70 – 3.10				
Foot Length	L	0.10	-	0.60		
Footprint	L1	0.35	-	0.80		
Foot Angle	ф	0°	-	30°		
Lead Thickness	С	0.08	0.08 – 0.26			
Lead Width	b	0.20 – 0.51				

Notes:

1. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.

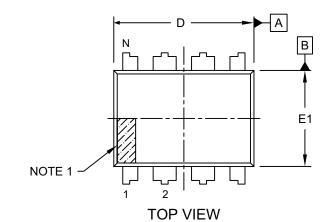
2. Dimensioning and tolerancing per ASME Y14.5M.

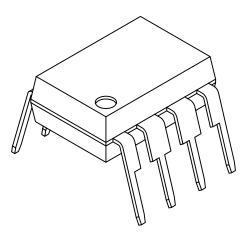
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

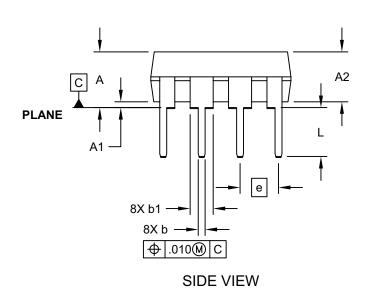
Microchip Technology Drawing C04-028B

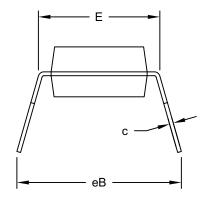
8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging







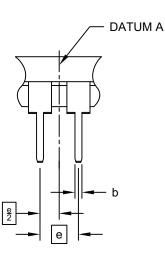


END VIEW

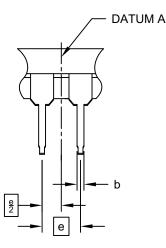
Microchip Technology Drawing No. C04-018D Sheet 1 of 2

8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging







Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	е	.100 BSC		
Top to Seating Plane	Α	-	-	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	-	-
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.348	.365	.400
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	С	.008	.010	.015
Upper Lead Width	b1	.040	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eВ	-	-	.430

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic
- 3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-018D Sheet 2 of 2

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
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